

a plurality of structure planes including at least one element structure plane;

electrically active elements disposed on said at least one element structure plane;

a first insulation layer disposed above said at least one element structure plane;

said first insulation layer having first contact holes disposed therein, and said first contact holes being filled with a metal;

a second insulation layer disposed above said first insulation layer;

said second insulation layer having second contact holes disposed therein and filled with electrical connecting leads, and said second contact holes being further filled with copper in a whole-area manner;

connection pieces disposed underneath said electrical connecting leads and above said first contact holes;

C1  
at least one diffusion blocker disposed underneath said electrical connecting leads, said diffusion blocker at least one of impeding and preventing a diffusion of copper, said diffusion blocker configured as a blocker layer interrupted only in a region having said first contact holes formed therein, said blocker layer disposed between said first insulation layer and said second insulation layer; and

said connection pieces being made of aluminum and covering said first contact holes and contacting said connection leads, and said connection pieces being covered by said second isolation layer.

SUB D1  
C2  
Claim 27 (amended). The integrated electrical circuit according to claim 1, wherein said blocker layer includes an upper surface facing said second isolation layer and a lower surface facing said structure plane, said connection pieces being in contact with said upper surface of said blocker layer.